

IN THE CLAIMS:

Please cancel claims 1-13 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 14-25 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-13. (Canceled)

14. (New) An electromagnetic wave shielding structure comprising:

- a) a transparent substrate having a top substrate face and a bottom substrate face;
- b) a mesh having a top mesh face and a bottom mesh face connected to the top substrate face; and
- c) a first layer of pressure sensitive adhesive having a top adhesive face and a bottom adhesive face connected to the top mesh face, the first layer of pressure sensitive adhesive being a predetermined thickness.

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15. (New) The electromagnetic wave shielding structure according to claim 14, further comprising a first mold-releasing film connected to the top adhesive face.

16. (New) The electromagnetic wave shielding structure according to claim 15, further comprising a second mold-releasing film connected to the bottom substrate face.

17. (New) The electromagnetic wave shielding structure according to claim 16, further comprising a second layer of pressure sensitive adhesive located between the second mold-releasing film and the bottom substrate face.

18. (New) The electromagnetic wave shielding structure according to claim 14, wherein the transparent substrate is a layer of polyethylene terephthalate.

19. (New) The electromagnetic wave shielding structure according to claim 14, wherein the transparent substrate is a layer of triacetate.

20. (New) A method for manufacturing an electromagnetic wave shielding structure, which comprises the steps of:

- a) pasting a bottom face of a mesh to a top face of the transparent substrate; and
- b) coating a first layer of pressure sensitive adhesive on a top face of the mesh, the mesh is located between the transparent substrate and the first layer of pressure sensitive adhesive.

21. (New) The method according to claim 20, further comprising the step of pasting a first mold-releasing film on a top face of the first layer of pressure sensitive adhesive, the first layer of pressure sensitive adhesive is located between the first mold-releasing film and the mesh.

22. (New) The method according to claim 21, further comprising the step of pasting a second mold-releasing film on a bottom of the transparent substrate, the transparent substrate is located between the second mold-releasing film and the mesh.

23. (New) The method according to claim 21, further comprising the steps of coating a second layer of pressure sensitive adhesive on a bottom of the transparent substrate, and pasting a second mold-releasing film on a bottom of the second layer of pressure sensitive adhesive, the second layer of pressure sensitive adhesive and the transparent substrate are located between the second mold-releasing film and the bottom substrate face.

24. (New) The method according to claim 20, wherein the transparent substrate is a layer of polyethylene terephthalate.

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25. (New) The method according to claim 20, wherein the transparent substrate is a layer of triacetate.